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PH5504A2NA1

Data Sheet
 R08DS0067EJ0100
 Rev.1.00
 Nov 05, 2012

Ambient Light Sensor

DESCRIPTION

The PH5504A2NA1 is an ambient light sensor with a photo diode and current amplifier. This product has spectral characteristics close to human eye sensitivity and outputs light current proportional to the ambient brightness.

The PH5504A2NA1 can be used to improve the performance and reduce the power consumption of digital equipment such as FPD-TV sets and mobile phones, by enabling automatic brightness control and automatic switching on and off of lighting systems.

FEATURES

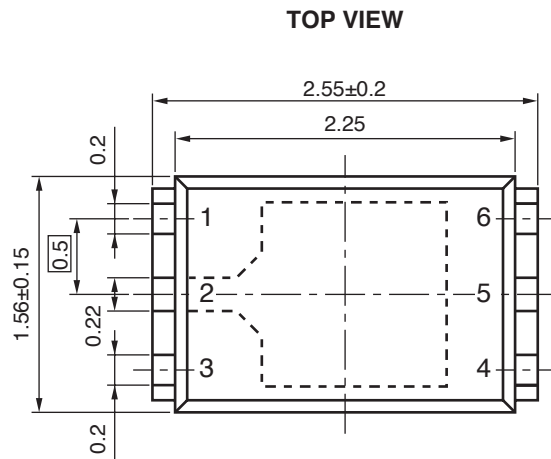
- Small and thin SON package 2.55 x 1.56 x 0.55 mm
- Spectral characteristics close to human eye sensitivity
 Peak sensitivity wavelength 530 nm TYP.
- The impact of infrared light can be reduced by incorporating infrared light correction circuits.
- Output characteristics proportional to illuminance
- Output light current 55 μ A TYP.@100 lx (Fluorescent light)
- Reduced variation of output current among light sources
- Low voltage operation $V_{CC} = 1.8$ to 5.5 V
- Pb-free

APPLICATIONS

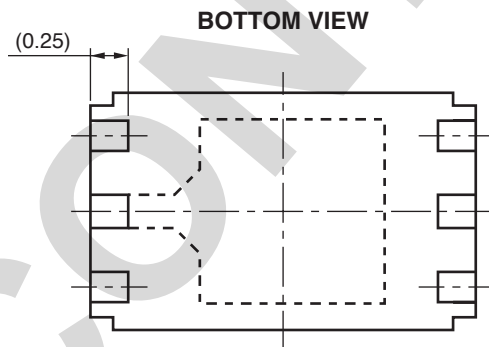
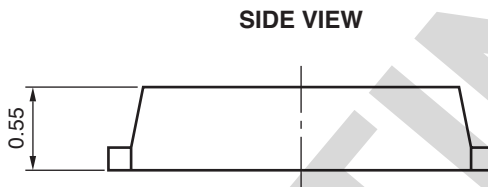
- FPD TV sets, displays
- Mobile phones, smartphones
- Notebook PCs, tablet PCs
- DSCs, DVCs
- FA equipment
- Lighting systems, etc.



PACKAGE DIMENSIONS (UNIT: mm)



Remark Pin 1 is distinguishable by the shape of the lead frame.

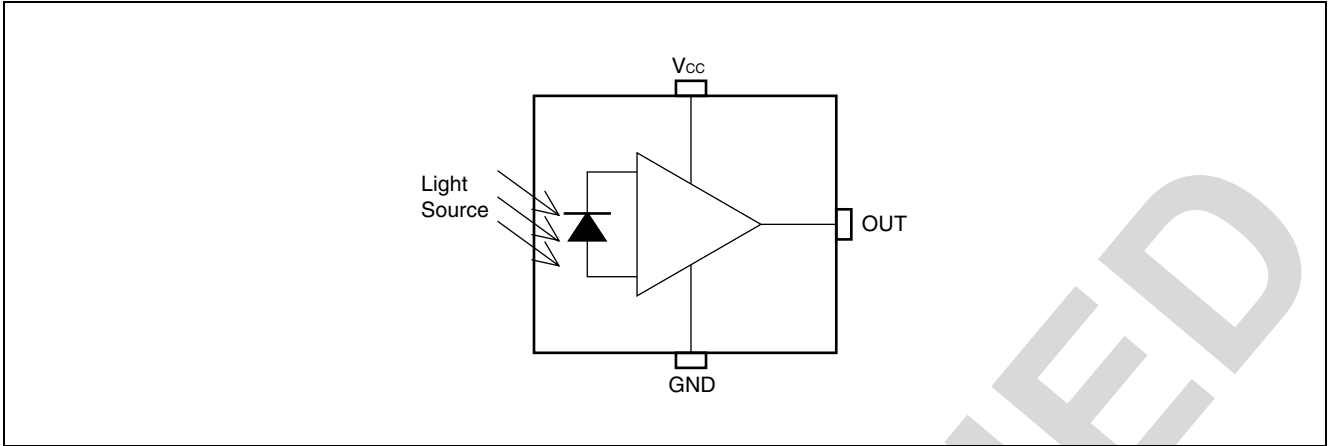


Remark () indicates nominal dimensions.

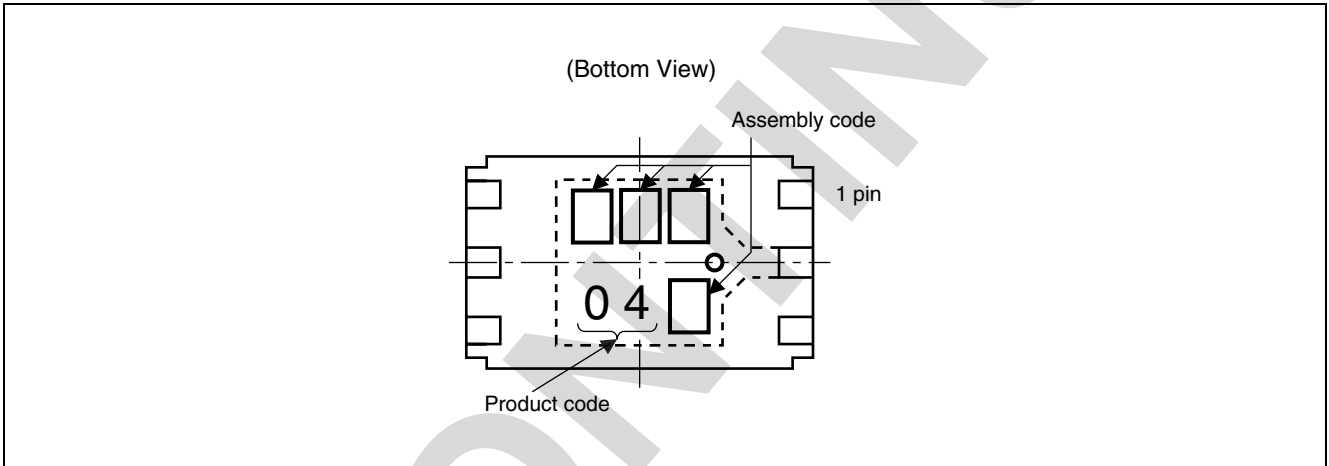
Pin No.	Terminal
1	OUT
2	GND
3	V _{CC}
4	NC
5	NC
6	NC

Remark 1. Connect all the NC terminals to GND or V_{CC}.
 2. The bypass capacitor between V_{CC} and GND is to be mounted within 20 mm of the package body.

BLOCK DIAGRAM



MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style
PH5504A2NA1-E4	PH5504A2NA1-E4-Y-A	Pb-Free	Embossed Tape 5 000 pcs/reel

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{CC}	6	V
Light Current	I _O	5	mA
Power Dissipation *1	P _D	135	mW
Operating Temperature	T _{opt}	-30 to +85	°C
Storage Temperature	T _{stg}	-40 to +100	°C

Note: *1. Mounted on glass epoxy board (18 mm × 13 mm × t_{0.8} mm)

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{CC}	1.8	3.0	5.5	V

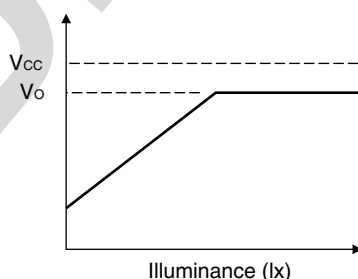
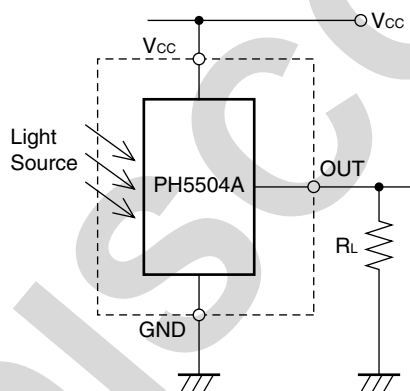
ELECTRO-OPTICAL CHARACTERISTICS (T_A = 25°C, V_{CC} = 3.0 V, unless otherwise specified)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Supply Current *1	I _{CC}	E _v = 100 lx *2	–	63	–	μA
Peak Sensitivity Wavelength	λ _p	–	–	530	–	nm
Light Current *1	I _{O0}	E _v = 0 lx	–	–	0.2	μA
	I _{O1}	E _v = 100 lx *2	44	55	66	μA
Sensitivity Ratio of Fluorescent/Incandescent	–	E _v = 100 lx	–	1	–	Multiple
Saturation Output Voltage *3	V _O	E _v = 100 lx, R _L = 150 kΩ *2	2.6	2.9	–	V
Switching Time *4	Rise Time	R _L = 5 kΩ *5	–	80	–	μs
	Fall Time		–	140	–	μs
	Delay Time		–	250	–	μs
	Storage Time		–	5	–	μs

Note: *1 Measured under load resistance conditions of an output current unsaturated

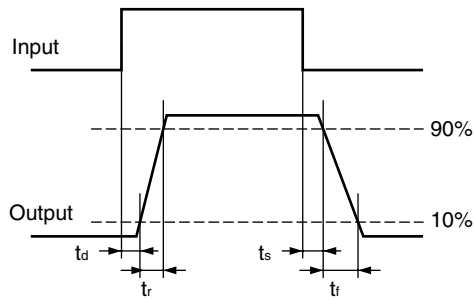
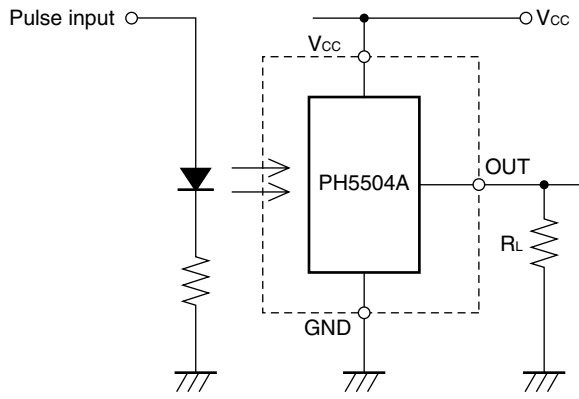
*2 Fluorescent light

*3 Saturation output voltage measurement method:



PH5504A2NA1

*4 Switching Time

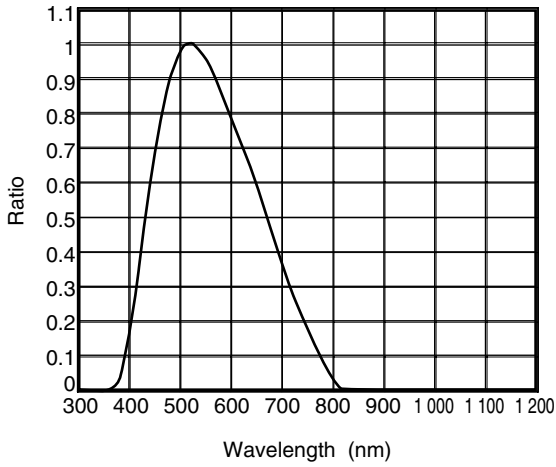


*5 White LED

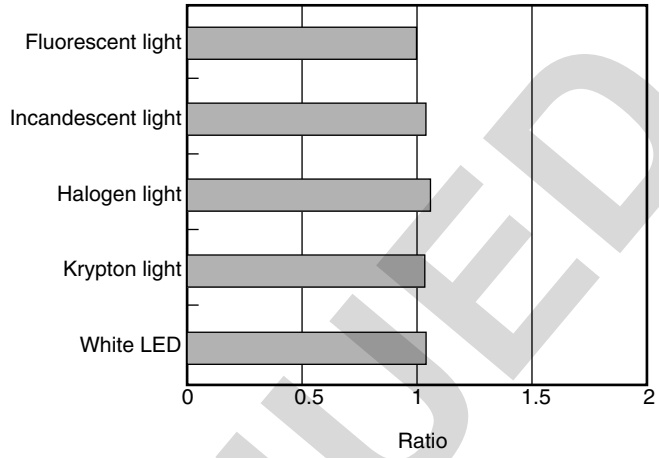
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TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, $V_{CC} = 3.0\text{ V}$, unless otherwise specified)

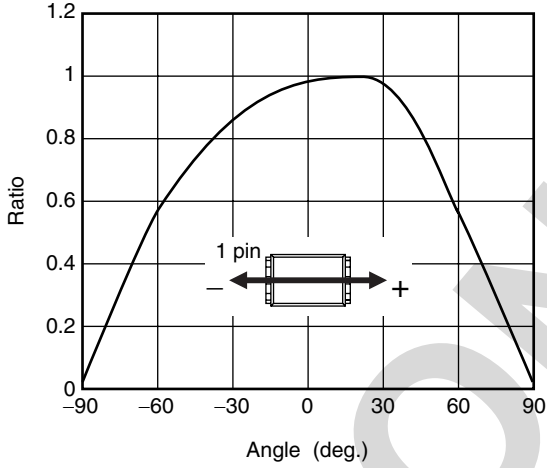
SPECTRAL SENSITIVITY CHARACTERISTICS



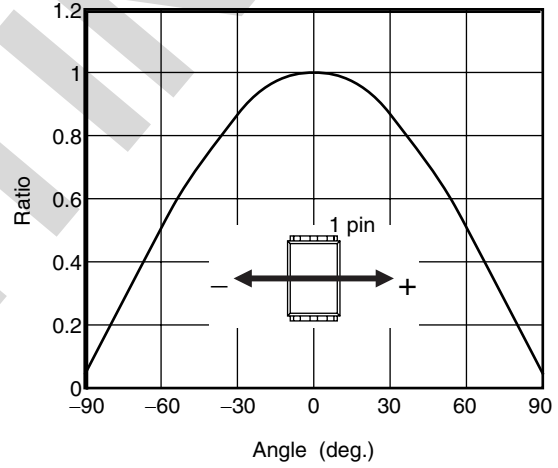
LIGHT SOURCE SENSITIVITY VARIATION



DIRECTIONAL CHARACTERISTICS 1

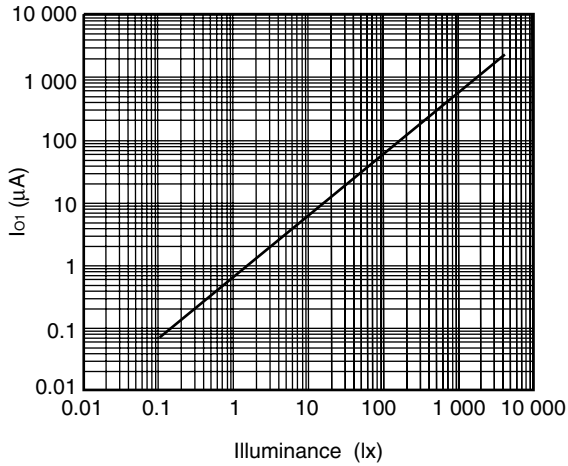


DIRECTIONAL CHARACTERISTICS 2

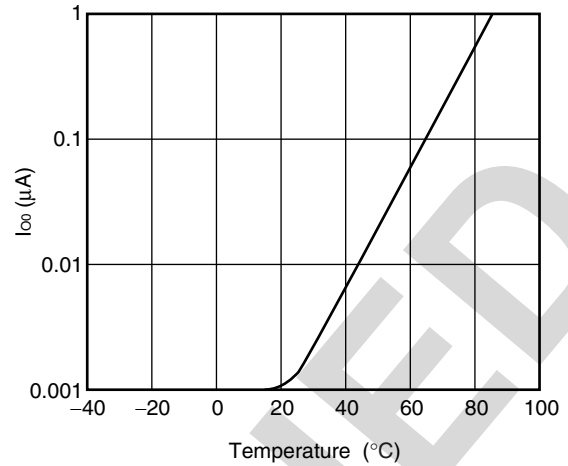


Remark The graphs indicate nominal characteristics.

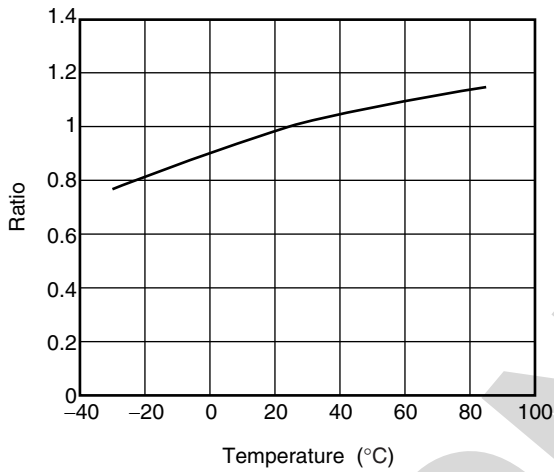
LIGHT CURRENT vs. ILLUMINANCE



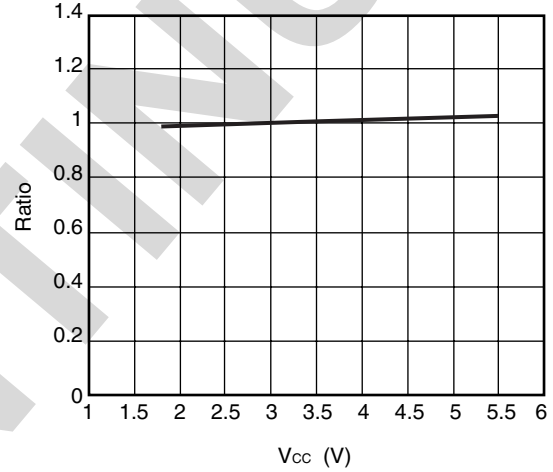
TEMPERATURE DEPENDENCY OF LIGHT CURRENT AT 0 lx



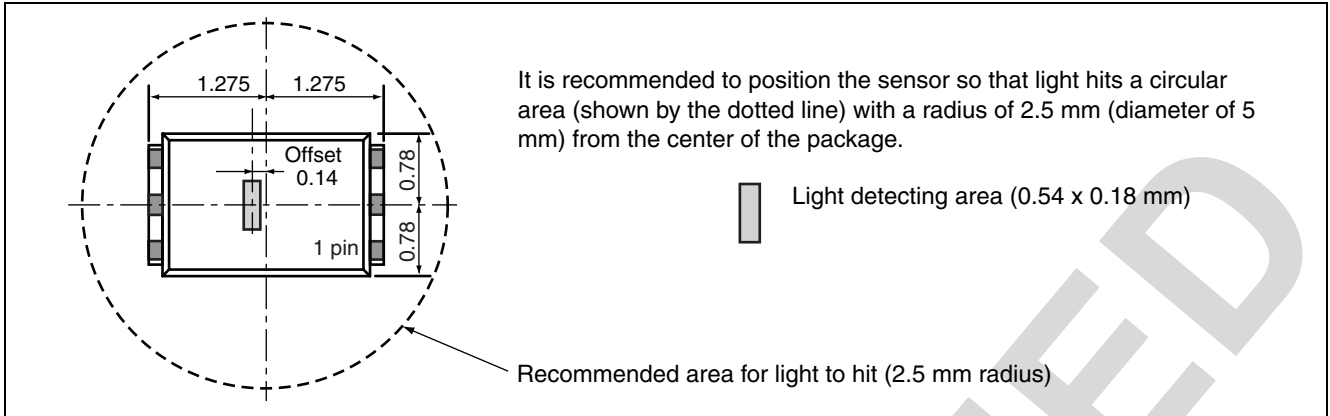
TEMPERATURE DEPENDENCY OF LIGHT CURRENT AT 100 lx (NORMALIZED AT 25°C)



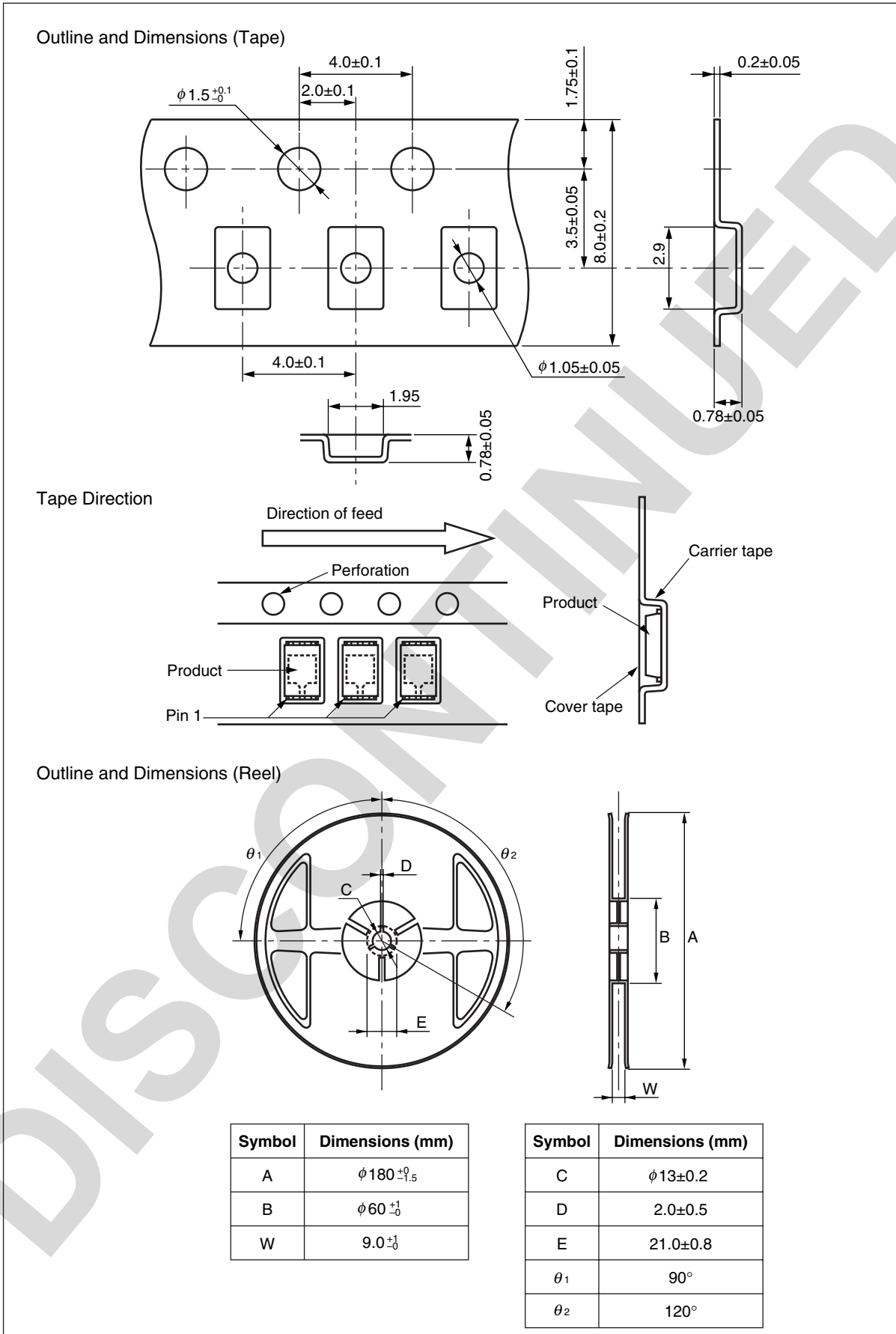
VCC DEPENDENCY OF LIGHT CURRENT AT 100 lx (NORMALIZED AT VCC = 3 V)



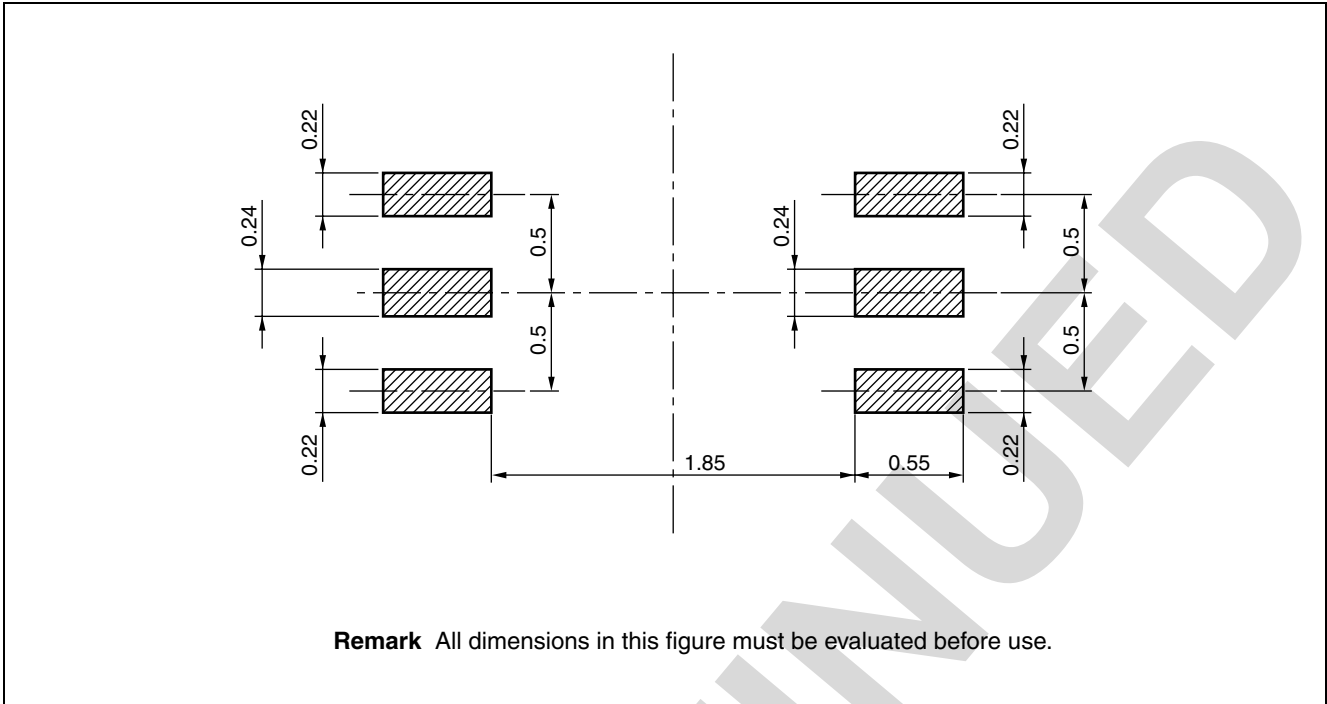
Remark The graphs indicate nominal characteristics.

RECOMMENDED OPTICAL LAYOUT (UNIT: mm)

TAPING SPECIFICATIONS (UNIT: mm)



RECOMMENDED MOUNT PAD DIMENSIONS (Unit: mm)



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NOTES ON HANDLING

1. Recommended reflow soldering conditions

(including infrared reflow, convection reflow, and infrared + convection reflow)

- (1) This product is dry-packed with desiccant in order to avoid moisture absorption.
- (2) After breaking the seal, reflow soldering must be done within 168 hours under the recommended temperature profile shown below.
- (3) If more than 168 hours have passed after breaking the seal, the baking process must be done by using a tape and reel.

Baking conditions: Once, with tape and reel, $60\pm 5^{\circ}\text{C}$, 10 to 24 hoursAfter the baking process, this product must be stored under conditions of 30°C or below, 70% RH or below, and reflow soldering must be done within 168 hours.

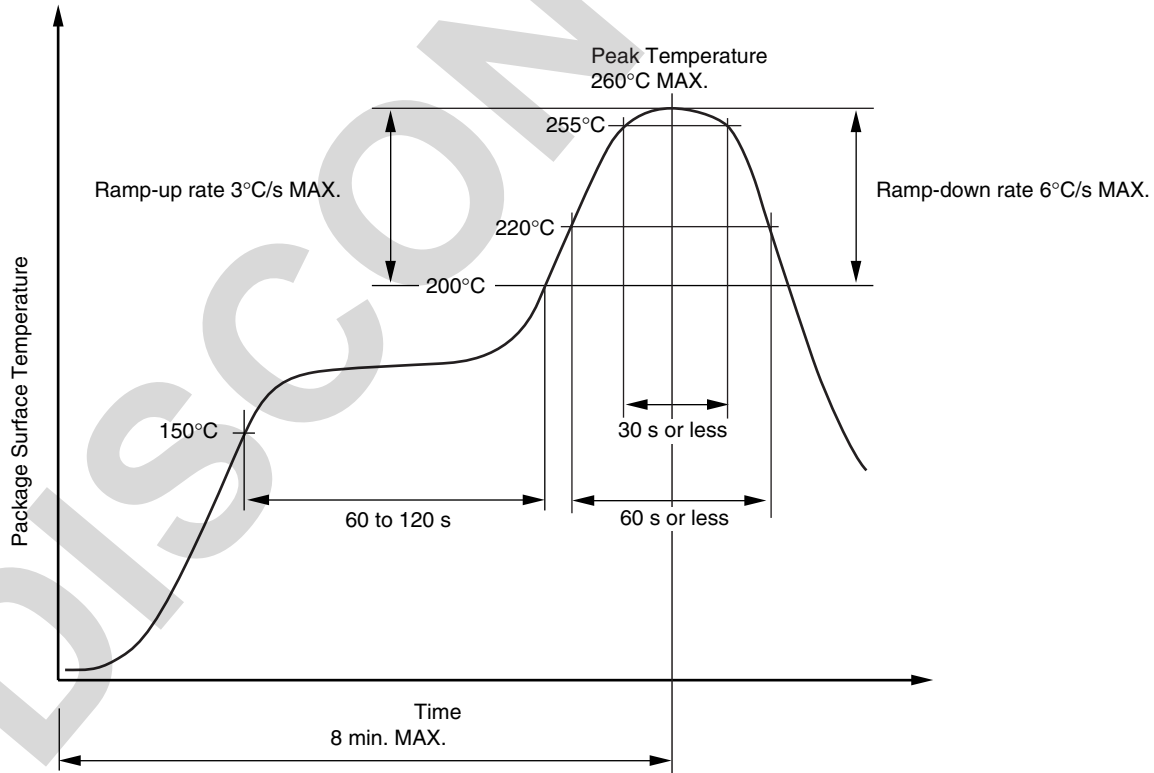
< Storage conditions after breaking seal >

- Storage conditions : 30°C or below, 70% RH or below
- Maximum storage period after breaking seal : 168 hours (Second reflow soldering must be completed within 168 hours.)

< Reflow soldering conditions >

- Peak reflow temperature : 260°C or below (Package surface temperature)
- Maximum number of reflows : 2
- No repair by hand soldering
- Maximum chlorine content of rosin flux (percentage mass) : 0.2% or less

Recommended Temperature Profile of Reflow



Revision History	PH5504A2NA1 Data Sheet
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Rev.	Date	Description	
		Page	Summary
1.00	Nov 05, 2012	-	First edition issued

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